

**2022**  
**Metallic Samples for RoHS**

**For XRF Monitor**

- \* Please note that the value of analysis is different depend on the lot.
- \* Please note that these samples are just monitor samples, not CRM.

**Form: DISK 20mm dia. X 10mm thick. (in 30mm dia. X 20mm thick resin)**

(Each 6 pcs/set)

		(ppm)					
		1	2	3	4	5	6
<b>AL Alloy (No. GAL1-6)</b>	Pb	<10	1010	298	87	1516	464
	Cd	<10	80	18	41	232	119
	Cr	<10	960	507	1543	94	220
<b>CU Alloy (No. GBR1-6)</b>	Pb	<10	779	303	99	1446	504
	Cd	<10	273	23	115	108	43
	Cr	<10	912	502	1392	83	152



\* Followings are non-resin mold

**Form: DISK 34mm dia. X 10mm thick. (5 pcs/set)**

		No.	Pb	Cr	
<b>Steel (No.JFEGR-FE-Set) (JSM M 102)</b>	SC1	< 0.010	< 0.010		(%)
	SC2	0.020	0.020		
	SC3	0.040	0.040		
	SC4	0.080	0.080		
	SC5	0.10	0.10		

(other components: C: 0.42-0.48%, Si: 0.15-0.35%, Mn: 0.60-0.90%, P: ≤0.030%, S: ≤0.035%)

**Form: DISK 34mm dia. X 10mm thick. (4 pcs/set)**

		No.	Sb	
<b>Stainless (No.JFEGR-Sb-Set) (JSM M 103)</b>	Sb1	<0.010		(%)
	Sb2	0.010		
	Sb3	0.050		
	Sb4	0.080		

**Form: DISK 34mm dia. X 10mm thick. (5 pcs/set)**

		No.	Pb	
<b>Stainless (No.JFEGR-SUS-Set) (JSM M 204)</b>	SUS 1	< 0.010		(%)
	SUS 2	0.020		
	SUS 3	0.040		
	SUS 4	0.080		
	SUS 5	0.10		

(other components: C: ≤0.08%, Si: ≤1.00%, Mn: ≤2.00%, P: ≤0.045%, S: ≤0.030%, Ni: 8.00-10.50%, Cr: 18.00-20.00%)

Form: DISK 34mm dia. X 10mm thick. (5 pcs/set) (%)

Ni Alloy (No.JFEGR-NI-Set) (JSM M 500)	No.	1	2	3	4	5
		Ni 1	Ni 2	Ni 3	Ni 4	Ni 5
	Pb	<0.010	0.020	0.040	0.080	0.10

Lead-Free Solder

Lead-Free Solder set: JSAC 0131 – JSAC 0134

Form: DISK: 40mm dia. X 4mm thick. (4 pcs/ set)

Item No.	Pb ( $\mu\text{g/g}$ )	Cd ( $\mu\text{g/g}$ )	Ag (%)	Cu (%)
JSAC 0131	13.9 $\pm$ 0.7	<3	0.488 $\pm$ 0.007	0.102 $\pm$ 0.002
JSAC 0132	520.9 $\pm$ 8.9	88.0 $\pm$ 3.2	2.98 $\pm$ 0.02	1.01 $\pm$ 0.02
JSAC 0133	1022 $\pm$ 19	832 $\pm$ 9	3.41 $\pm$ 0.02	0.756 $\pm$ 0.009
JSAC 0134	2007 $\pm$ 25	1530 $\pm$ 17	3.91 $\pm$ 0.03	0.513 $\pm$ 0.009